IPC - ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Form Type *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
upplier Inform	nation						·								
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2025-06-08				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env-Stewa	ards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorized Represe	entative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	er Item Number			Mfr Item Name			Effective Date	Version	Manufacturing Site		,	Weight*	UOM	Unit Type	
				6PB RP SNUB SM	PB RP SNUB SMD VDE		2025-06-08 LITEONFG		LITEONFG	537.109		mg	Each		
	Process Informatio		amainal Daga	Allow	STD-020 MSL	Dating	Dools Droo	aga Dadw T	·	May Time at Pack	Tomamount	Numa Numah	per of Reflow Cyc	alac	
		Terminal Base Alloy J-STD-02 CU Alloy 1		S1D-020 MSL	Rating	Peak Process Body Temper						ber of Reflow Cyc	cies		
	n (Sn) - annealed	C	U Alloy	1			200		<u>lc</u>	30	secon	ds   3			
omments	·		J :- 10 1	201-											
	ime at peak temperature														
<i>r</i> more informatio	on regarding material co	mposition p	olease refer to	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appl											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	1.83	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.635	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.888	mg
			Supplier	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0		0.307	mg
Die	4.043	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.283	mg
			Supplier	Silicon (Si)	7440-21-3		3.76	mg
Die Attach	1.665	mg	Supplier	Silver (Ag)	7440-22-4		1.2487	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.4162	mg
Lead Frame	108.322	mg	Supplier	Silver (Ag)	7440-22-4		0.68	mg
			Supplier	Zinc (Zn)	7440-66-6		0.13	mg
			Supplier	Iron (Fe)	7439-89-6		2.48	mg
			Supplier	Copper (Cu)	7440-50-8		105	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-Black	298.368	mg	В	Brominated Bisphenol A Diglycidyl Ethe	er 40039-93-8		5.9674	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		4.4755	mg
			Supplier	Carbon Black (C)	1333-86-4		1.4918	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		211.8413	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		52.2144	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		22.3776	mg
Mold Compound-White	116.032	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		23.2064	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		81.2224	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		11.6032	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.149	mg	Supplier	Gold (Au)	7440-57-5		0.149	mg